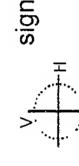


### lectro-Optic Field-Mapping System **OUT3** S N 2 $\angle 22.5^{\circ}$ $\lambda/4 loop$ fiber coupler <u>(45+δ)</u>° (22.5+ 8)° Polarization Control OUT2 0 $\lambda/2$ loop BS $(22.5+\theta)^{\circ}$ - IN7 N2 WP 67.5° Fiber-Based El IN2 optical isolator photo diode $(22.5+\theta+\delta)^{\circ}$ Ĭ OUT5

detection (input) beam polarization (w.r.t. horizontal axis)



signal (reflected) beam

(w.r.t. horizontal axis)

FIG. 2

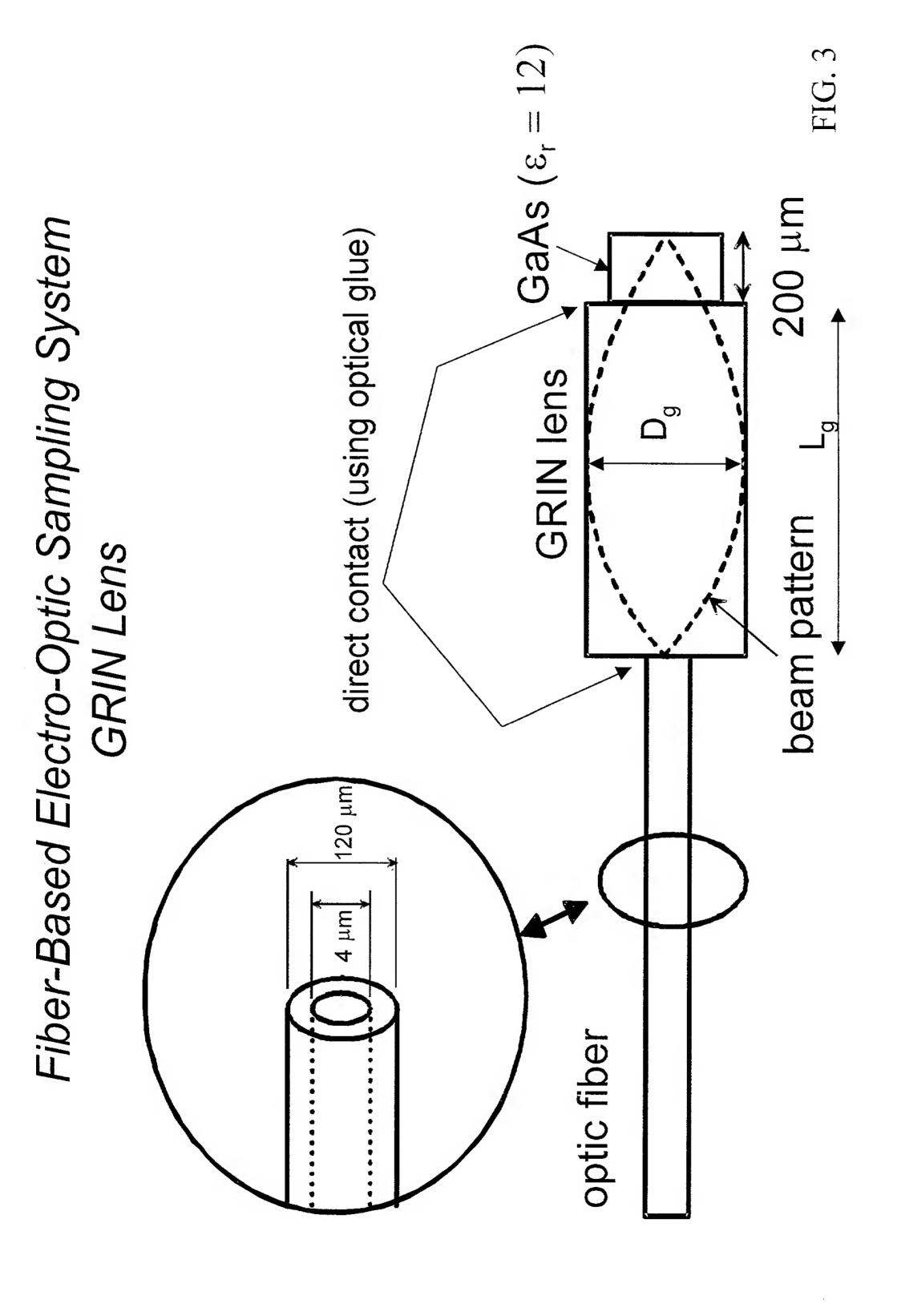
GaAs tip

9NI

**GRIN** Lens

e-mode optical fiber

singl



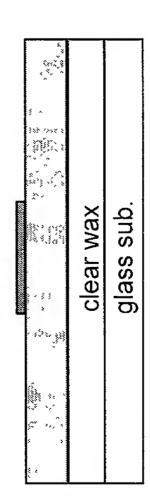
### Fiber-Based Electro-Optic Sampling System Probe Tip Fabrication Procedure

GaAs = (100) or (110)

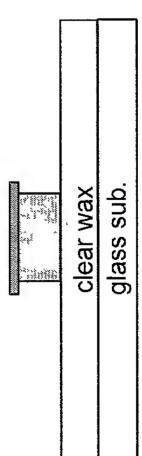
PR 1827 : 3.5 Krpm (30 sec), 105 C (1 min)

clear wax glass sub. expose without mask (15 sec), develope (90 sec)

PR 1827 : expose (15 sec), develope (50 sec), hard bake (105 C, 1 min)

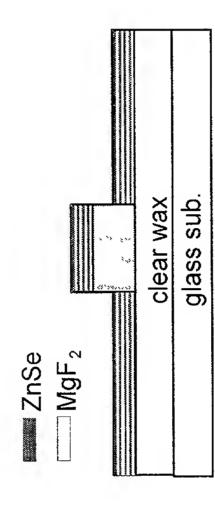


mount sample on glass substrate using clear wax (on the 150 Chot plate)



wet etching: H 2SO4: H2O2: H2O = 1 . 8 . 1

+ few drops of NH 4OH agitate 30 sec every 30 sec change etchant every 10 min.



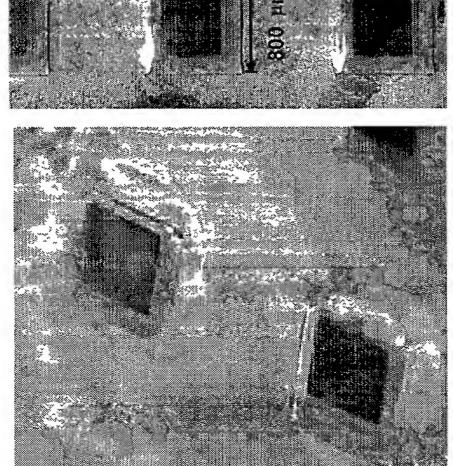
Distributed Bragg Reflector (DBR) deposition MgF 2 = 1,403 Å, ZnSe = 833 Å x 4 sets

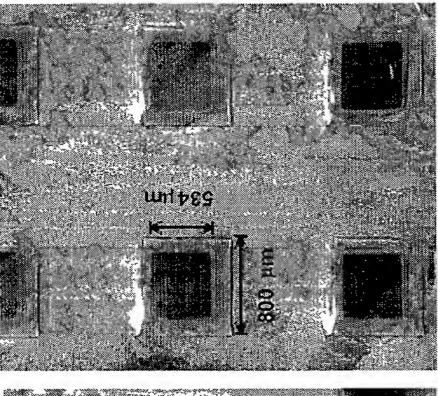


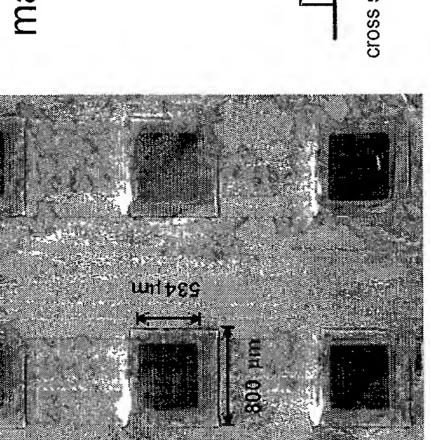
Final probe tip (released in the hot aceton)

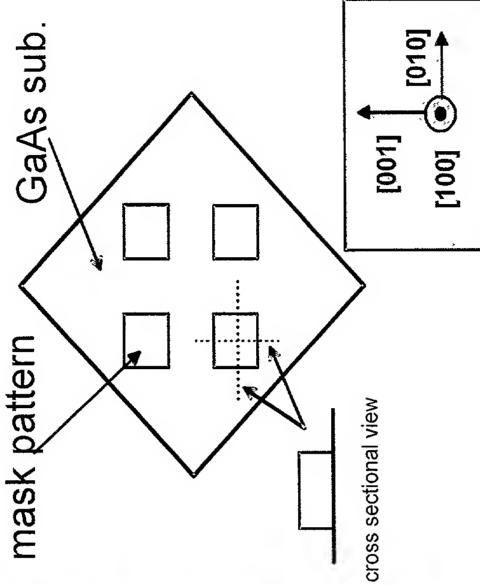
FIG. 4

# ectro-Optic Sampling System Fabrication - (100) GaAs Fiber-Based Ele Probe Tip

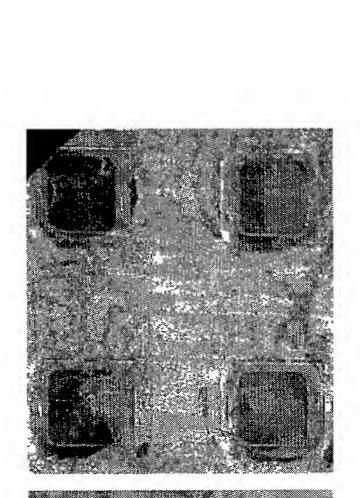


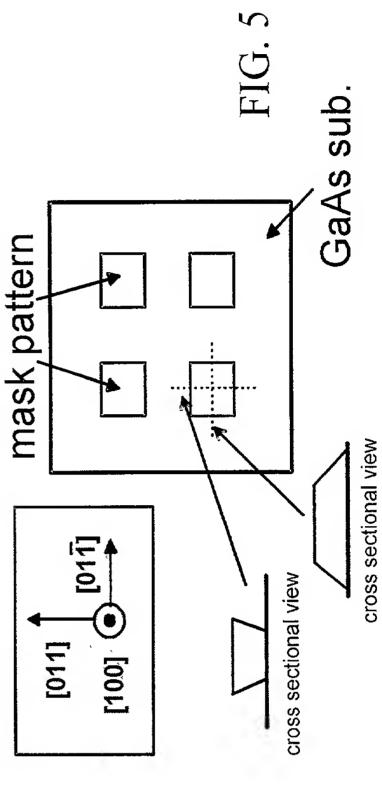




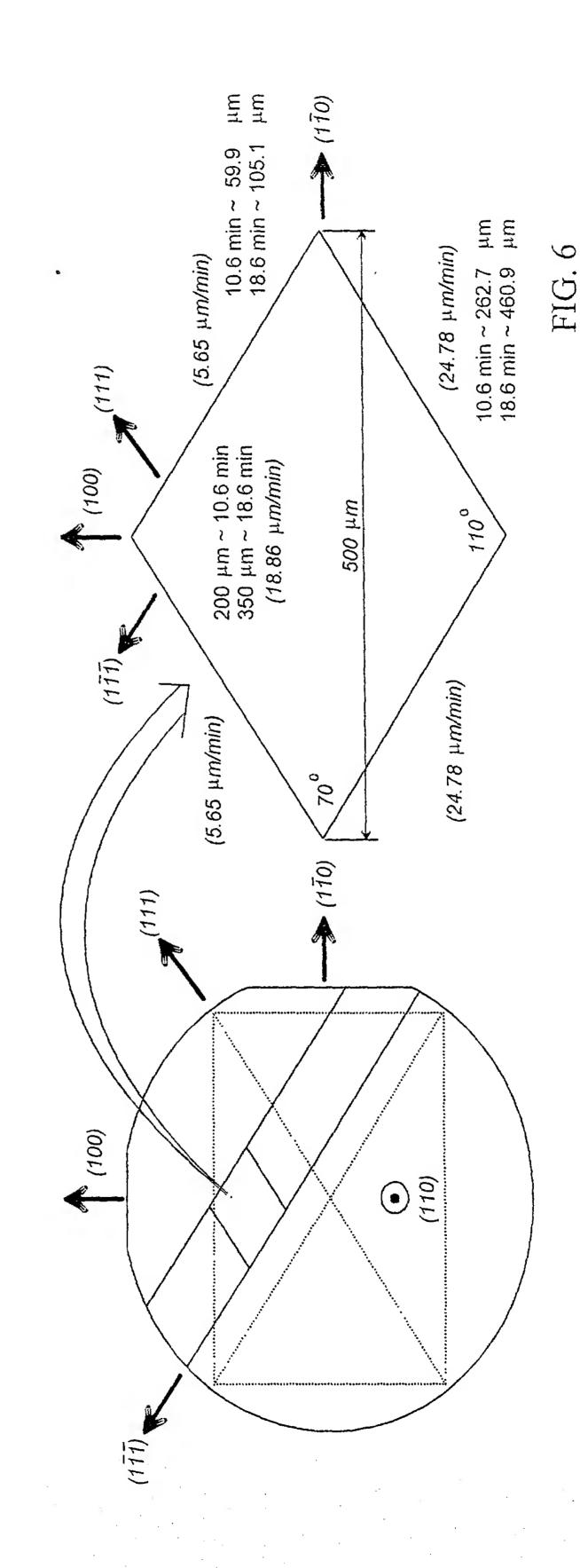


μm/min x 20 min) μm/min) 0 μm (7.95 μm, 6.5~7.5 etching depth ~ 160 (lateral : 130~150

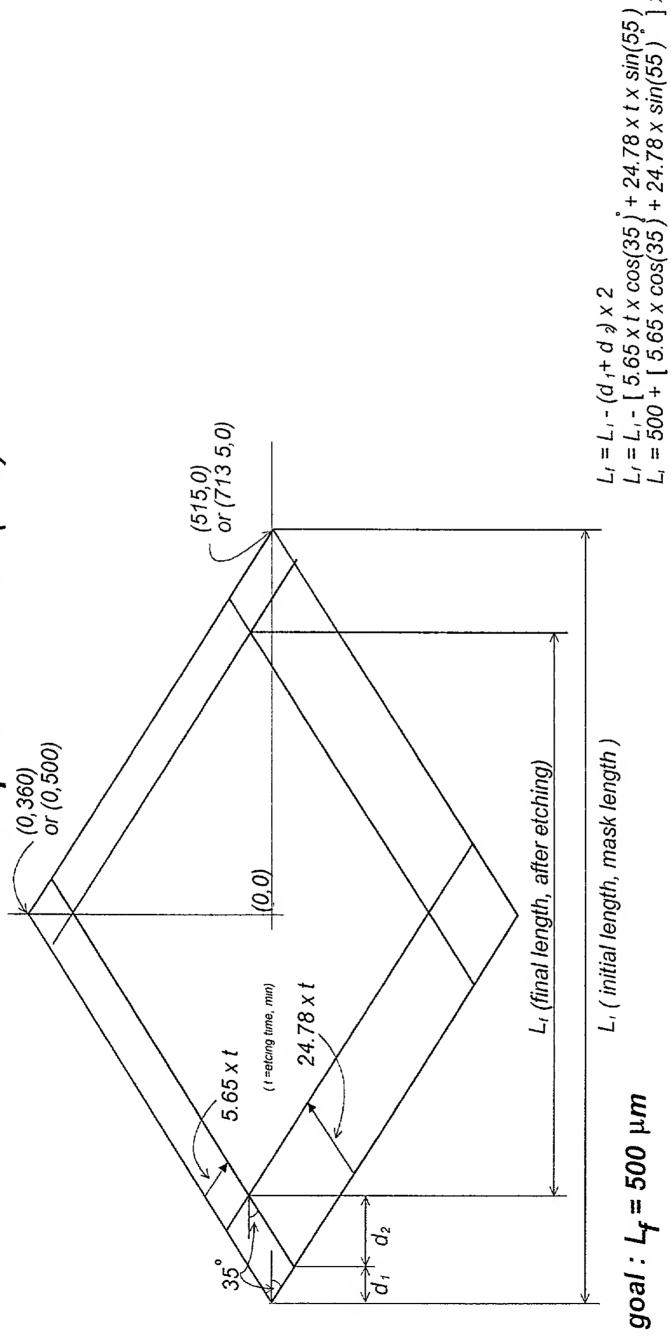




Fiber-Based Electro-Optic Sampling System Probe Tip Fabrication - (110) GaAs



## -Based Electro-Optic Sampling System Probe Tip Fabrication - (110) GaAs Fiber-Based



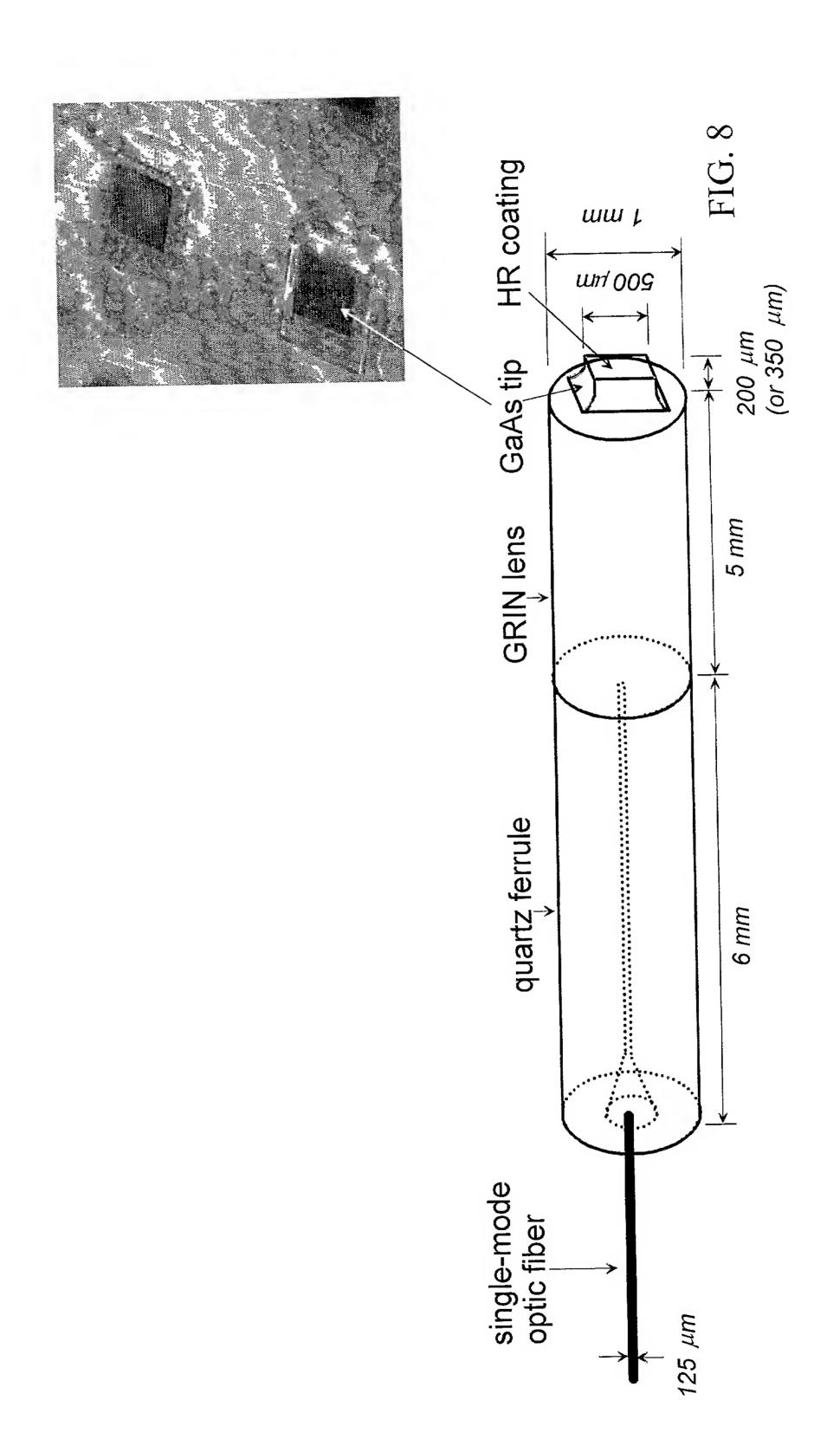
 $\begin{bmatrix} 5 \end{bmatrix} \hat{\ \ } \begin{bmatrix} x \ 2 \end{bmatrix} = 500$  $\begin{bmatrix} x \ 2 \ x \ t \end{bmatrix}$ 

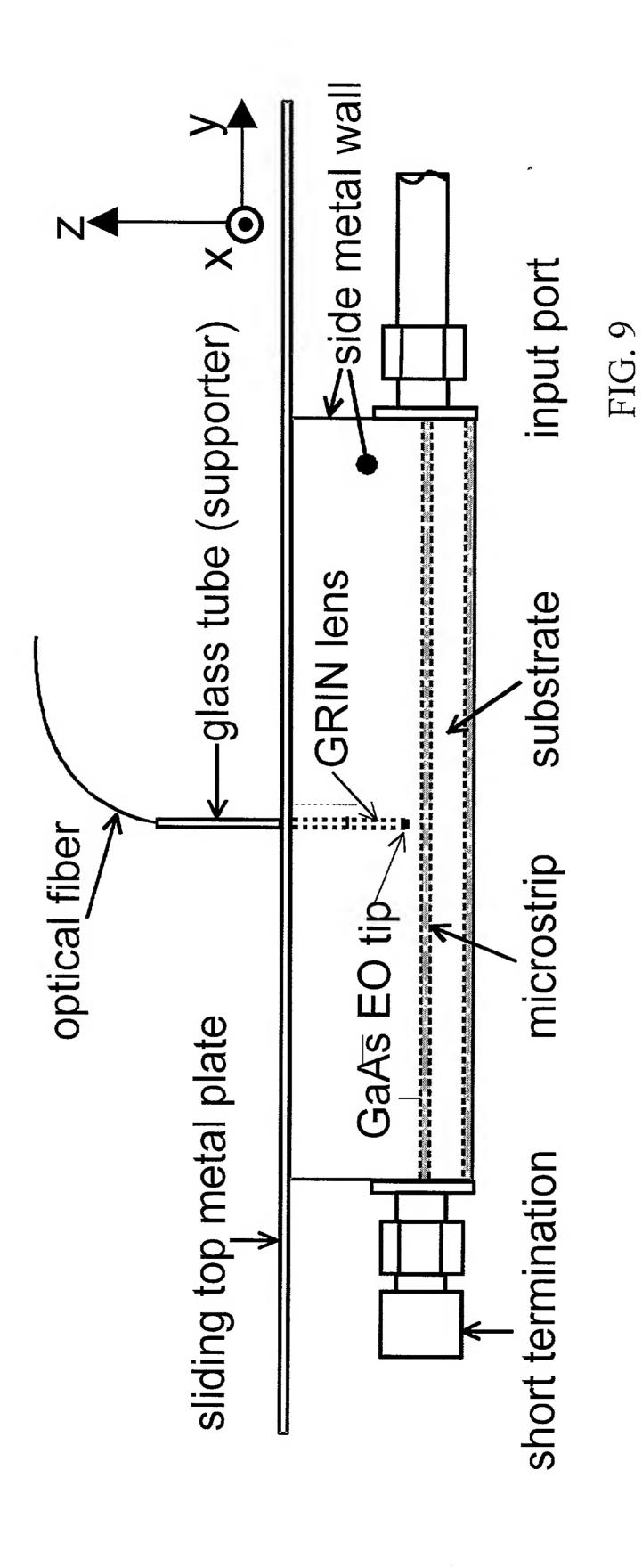
μ*m wafer* μ*m wafer* 

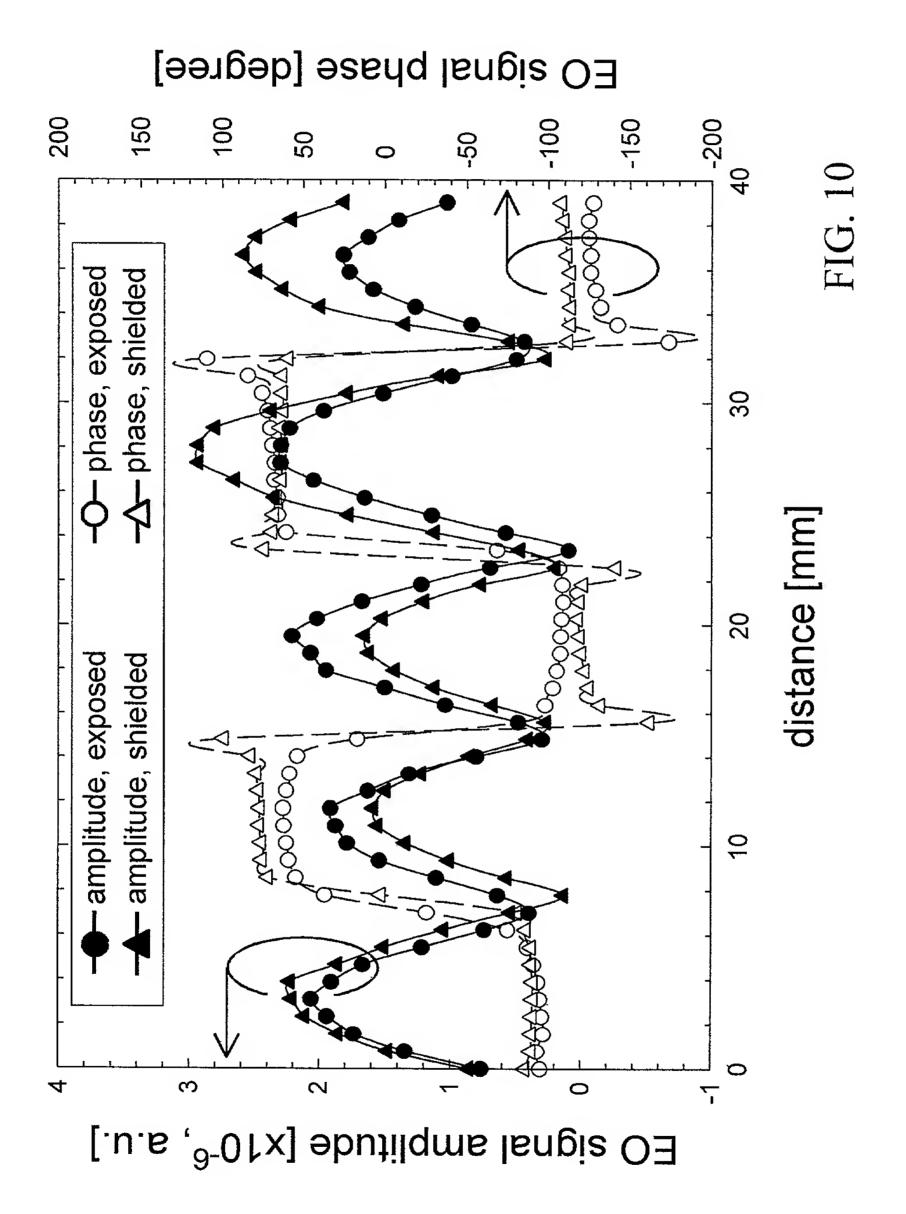
t = 200 / 18.86 (μm/min) = 10.6 min for 200 t = 350 / 18.86 (μm/min) = 18.6 min for 350 ( t = etching time, min)

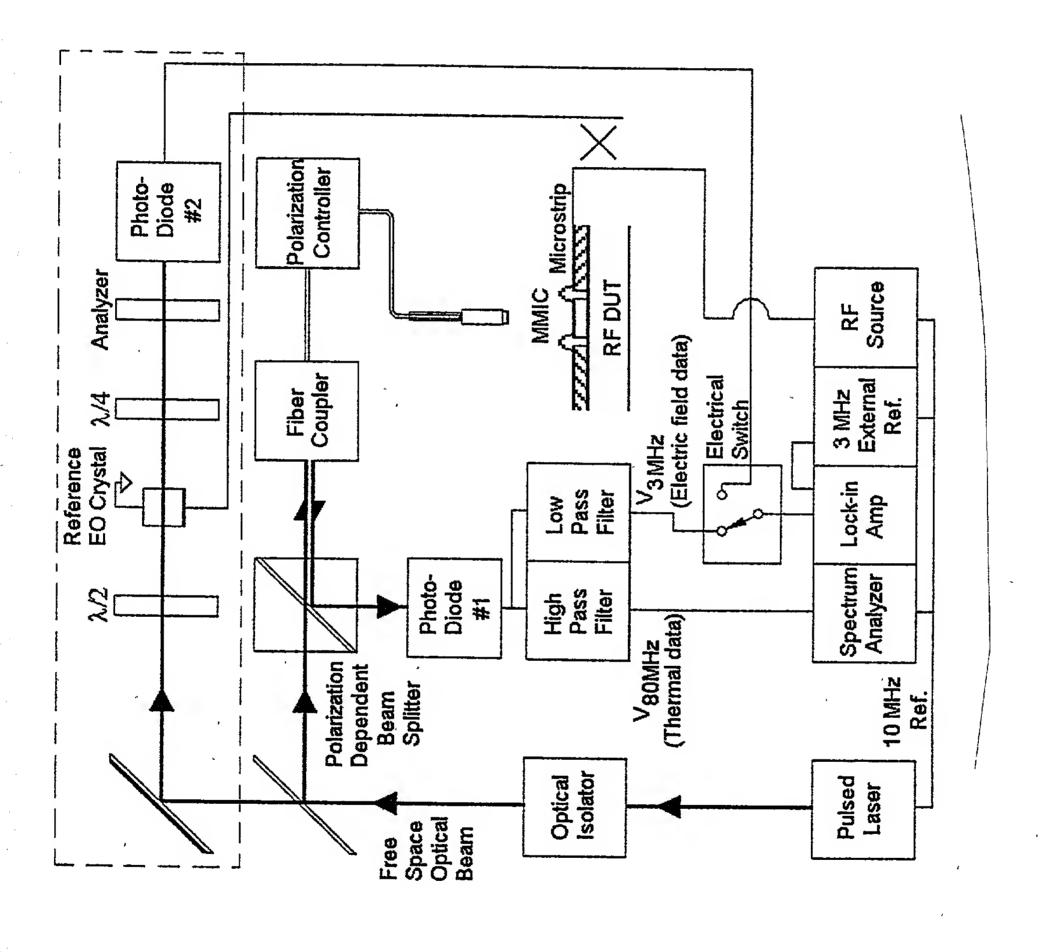
 $L_{\rm r} = 1029~\mu m$  for 200  $\mu m$  wafer, = 1427  $\mu m$  for 350  $\mu m$  wafer

Fiber-Based Electro-Optic Sampling System Probe Head Assembly

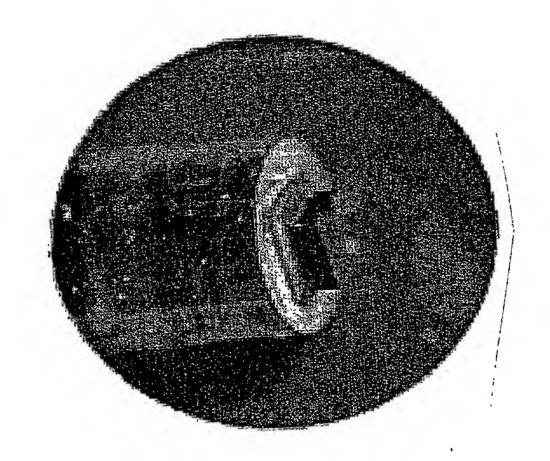




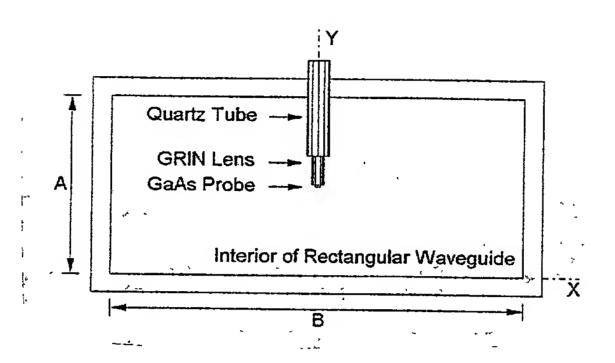




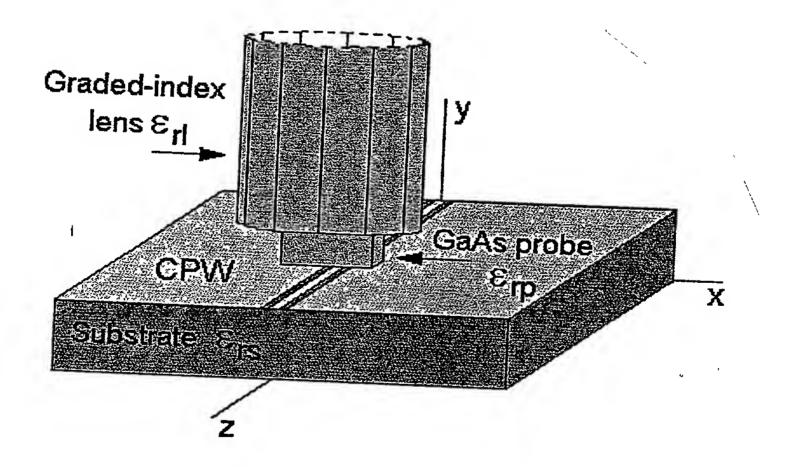
コープロー



F1217

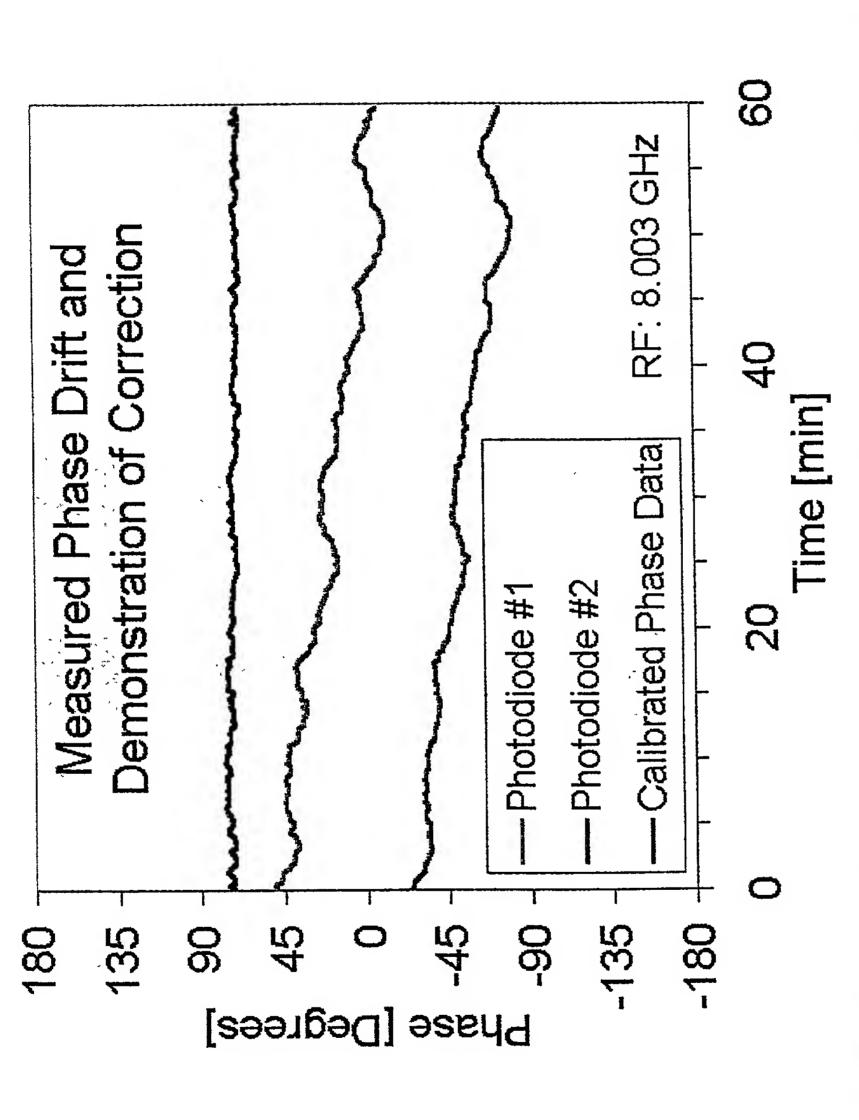


F1413



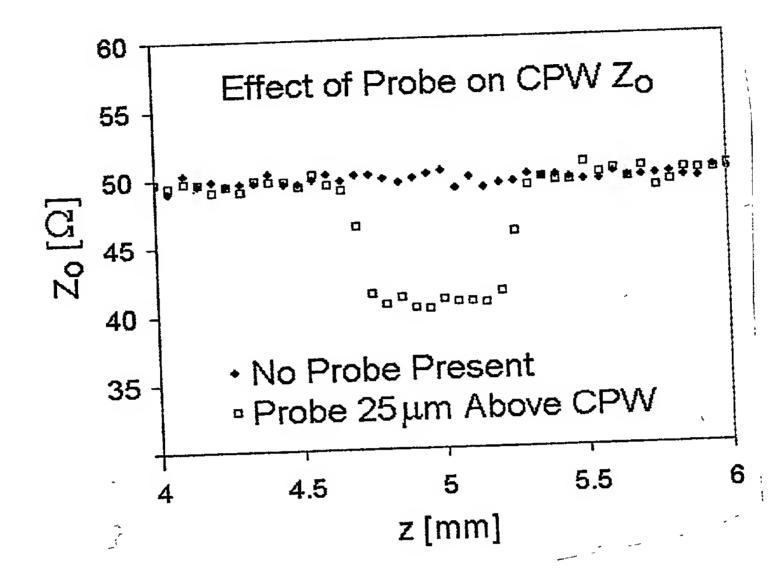
F1614

# zation - Electric Field Phase Character

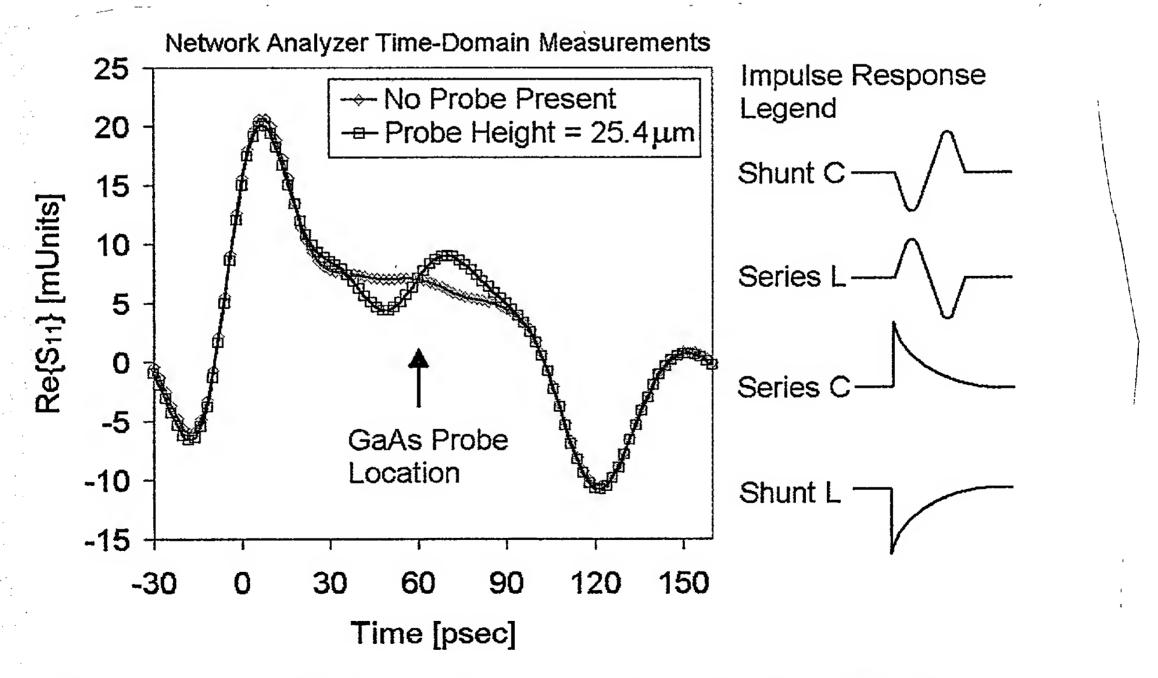


measured temporal phase stability is ±3° Over one hour,

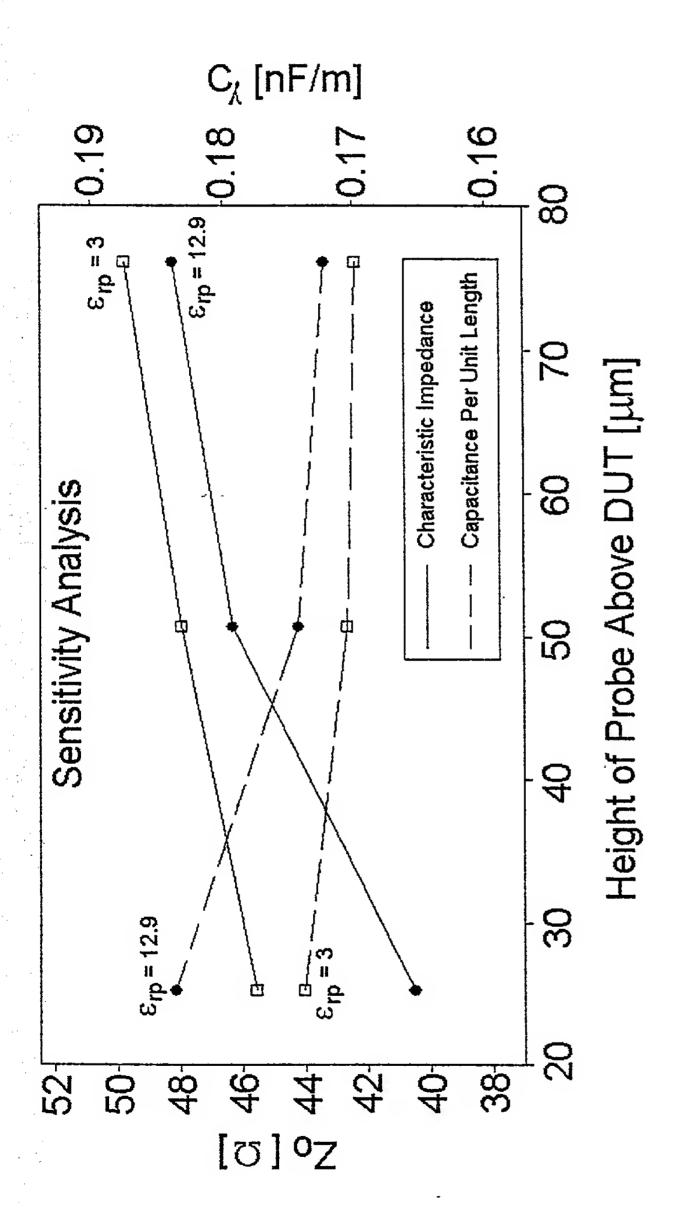
MA ID

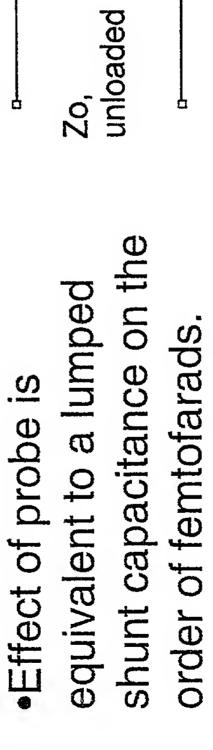


F1616



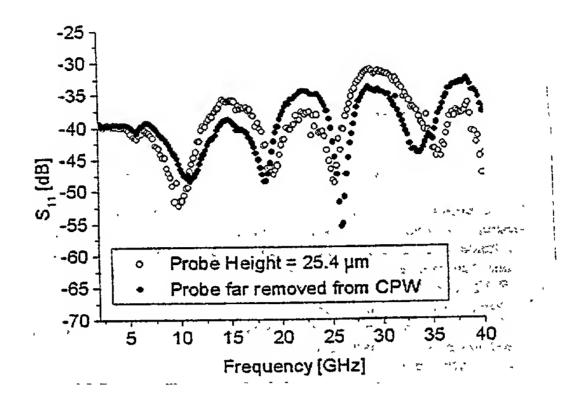
•Frequency domain measurements (2 - 40 GHz): |S11| < -30 dB with and without probe.



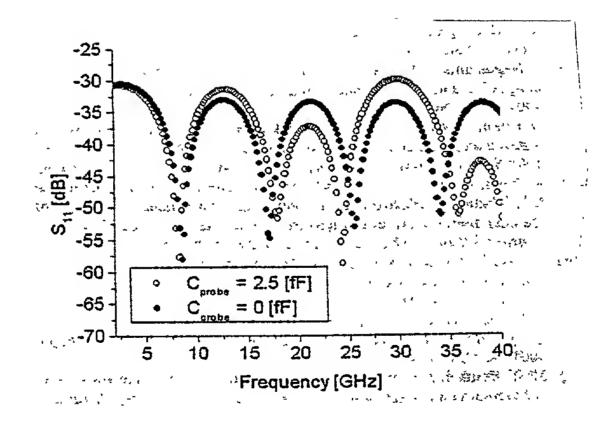


Zo, zo, unloaded Cprobe

上210g

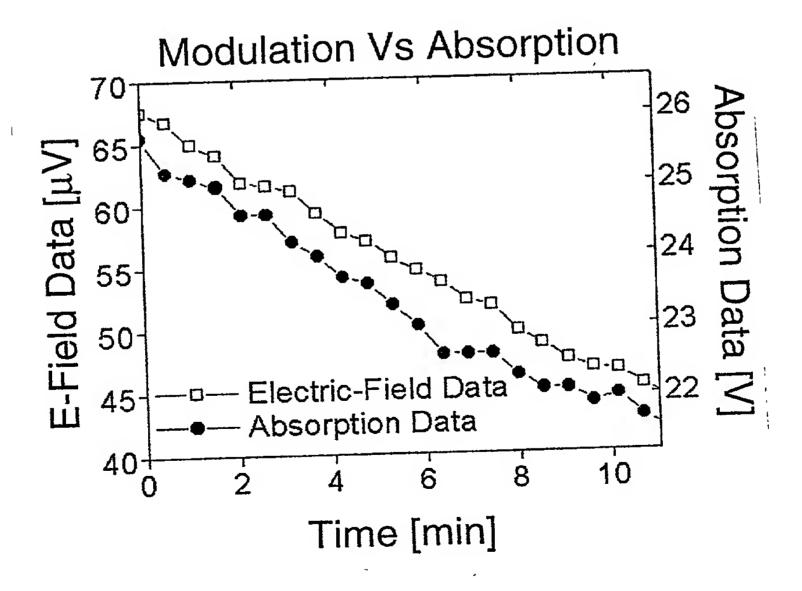


F1619

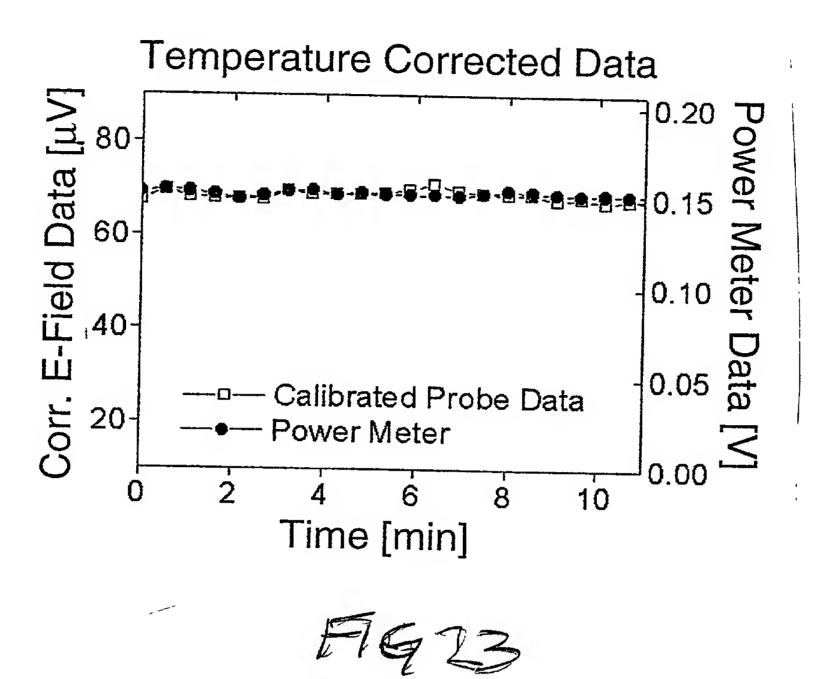


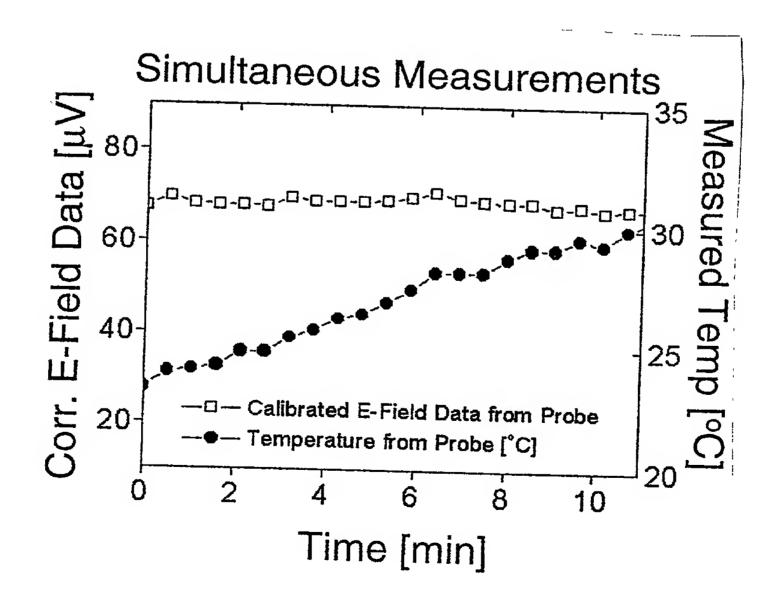
F1620

F1621



F1922





F16 Z4